

■ Description

The **17-21** SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained. and the package quantity 3000pcs/reel.

■ Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with infrared and vapor phase reflow solder process.
- Compatible with automatic placement equipment .
- Mono-color type.

■ Applications

- Backlighting.
- Indicator.
- LCD.
- General use.

■ Absolute Maximum Ratings (at Ta=25°C)

Parameter	Symbol	Maximum Rating	Unit
Power Dissipation	P _D	72	mW
Forward Current	I _F	30	mA
Peak Forward Current (Pulse width ≤ 100 μS duty ≤ 1/10)	I _{FP}	60	mA
Reverse Voltage	V _R	5	V
Operation Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +90	°C
Soldering Temperature	Tsol	Hand Soldering: 260°C for 5s	°C

■ Basic Characteristics

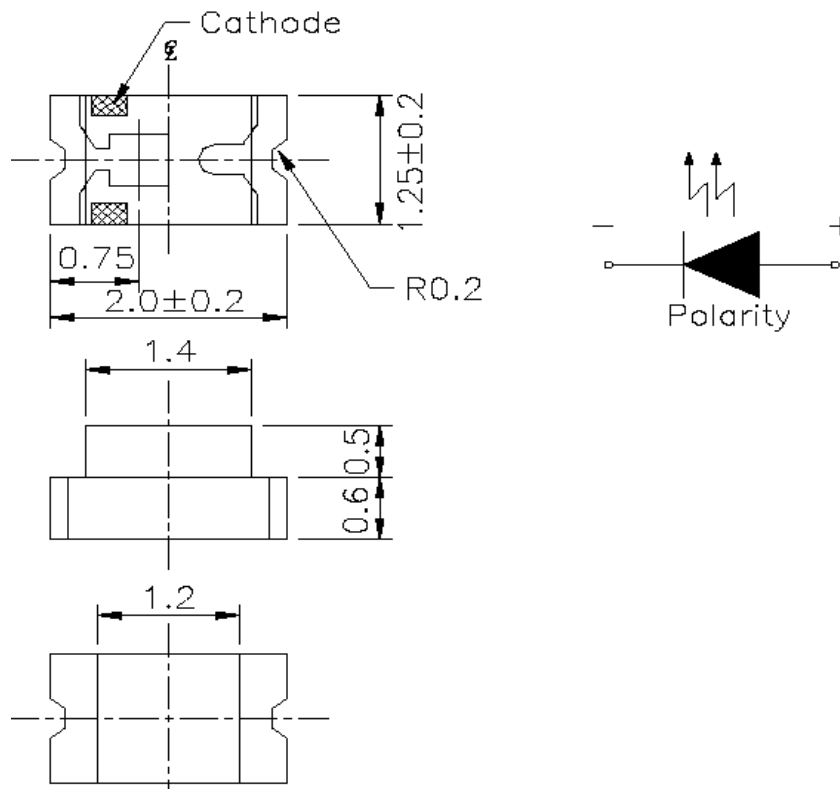
0805 Package Chip LED

LK17-21VGC/TR8

 $T_a=25^{\circ}\text{C}$

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	--	2.0	2.4	V
Reverse Current	I_R	$V_R=5\text{V}$	--	--	10	μA
Dominant Wavelength	λ_D	$I_F=20\text{mA}$	--	571	--	nm
Peak Wavelength	λ_P	$I_F=20\text{mA}$	--	570	--	nm
Spectral Bandwidth	$\Delta\lambda$	$I_F=20\text{mA}$		30		nm
Luminous Intensity	I_V	$I_F=20\text{mA}$		50	--	mcd
50% View Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	--	140	--	deg

■ Package Dimensions



Notes: without special declared, the tolerance is $\pm 0.2\text{mm}$

■ Typical Electrical / Optical / Characteristics Curves

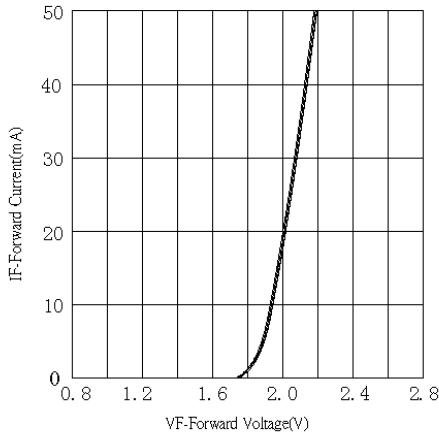


Fig.1 Forward Current vs.Forward Voltage

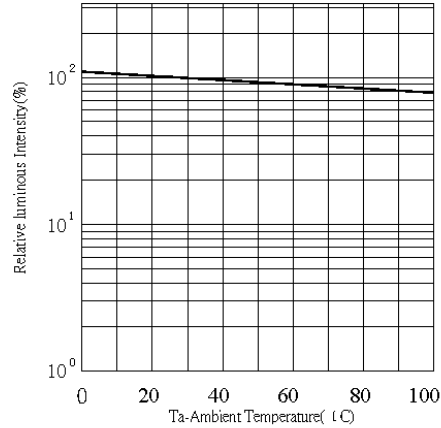


Fig.2 Relative luminous Intensity vs.Ambient Temperature

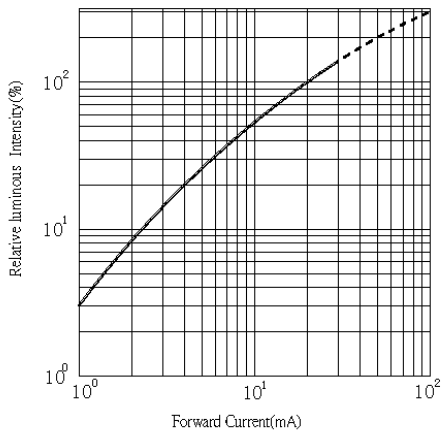


Fig.3 Relative luminous Intensity vs.Forward Current

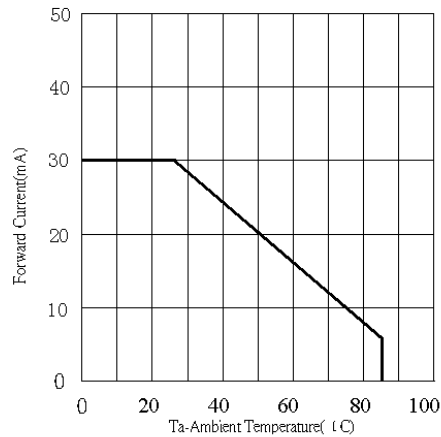


Fig.4 Forward Current vs.Ambient Temperature

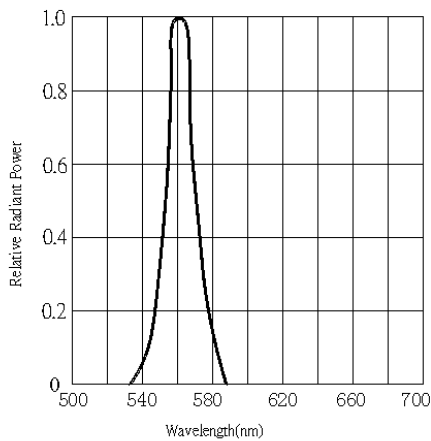


Fig.5 Relative Radiant Power vs.Wavelength

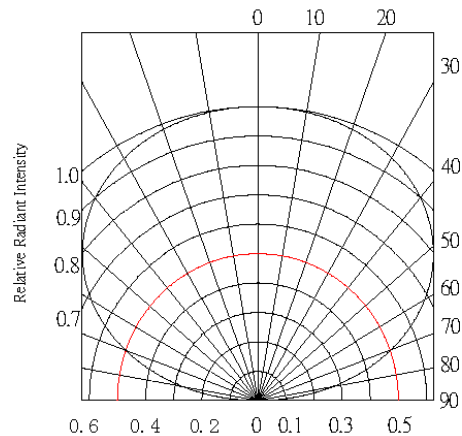


Fig.6 Relative Radiant Intensity vs.Angular Displacement